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Title:Far field subwavelength imaging of magnetic patterns

Authors:Ourir, A. (1); Lerosey, G. (1); Lemoult, F. (1); Fink, M. (1); de Rosny, J. (1)

Author affiliation:(1) Lab. Ondes et Acoust., ESPCI, Paris, France

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Abstract:Far field imaging of subwavelength magnetic objects in real time is a very challenging issue. We propose an original solution based on a planar array of closely spaced split ring resonators. Hybridization between the resonators of such metalens induces subwavelength modes with different frequencies. Thanks to these high Q resonating modes, Purcell like effect allows an evanescent source, close to the metalens, to emit waves that can be collected efficiently in the far field. We present the first microwave experimental demonstration of such metalens to image of a subwavelength magnetic pattern. Numerical simulation shows that this approach is still valid at THz frequencies.

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